L Number	Hits	Search Text	DB	Time stamp
1	14	(barrier$2) near7(wet adj2 etch$4) and ((contact$2 adj hole$2 via adj hole$2 through adj hole$2) same((barrier$2 liner$2)with (titanium aluminum "tio.sub.2" "al.sub.2o.sub.3")))	USPAT; US-PGPUB	2004/08/06 18:21
2	1878	((contact$2 adj hole$2 via adj hole$2 through adj hole$2) same((barrier$2 liner$2)with (titanium aluminum "tio.sub.2" "al.sub.2o.sub.3")))	USPAT; US-PGPUB	2004/08/06 18:07
3	14	(barrier$2) near7(wet adj2 etch$4) and (((contact$2 adj hole$2 via adj hole$2 through adj hole$2) same((barrier$2 liner$2)with (titanium aluminum "tio.sub.2" "al.sub.2o.sub.3"))))	USPAT; US-PGPUB	2004/08/06 18:22
4	46	((contact$2 adj hole$2 via adj hole$2 through adj hole$2) same((barrier$2 liner$2)with (titanium aluminum "tio.sub.2" "al.sub.2o.sub.3")))and (atomic adj layer adj depost$4 ald)	USPAT; US-PGPUB	2004/08/06 18:22
5	68	((barrier$2) near4 (bottom lower)) near7(etch$4) and ((contact$2 adj hole$2 via adj hole$2 through adj hole$2) same((barrier$2 liner$2)with (titanium aluminum "tio.sub.2" "al.sub.2o.sub.3")))	USPAT; US-PGPUB	2004/08/06 18:28
6	61	(plug$2 fill$4)and (((barrier$2) near4 (bottom lower)) near7(etch$4) and ((contact$2 adj hole$2 via adj hole$2 through adj hole$2) same((barrier$2 liner$2)with (titanium aluminum "tio.sub.2" "al.sub.2o.sub.3"))))	USPAT; US-PGPUB	2004/08/06 18:18
7	5	((plug$2 fill$4)and (((barrier$2) near4 (bottom lower)) near7(etch$4) and ((contact$2 adj hole$2 via adj hole$2 through adj hole$2) same((barrier$2 liner$2)with (titanium aluminum "tio.sub.2" "al.sub.2o.sub.3"))))) and (atomic adj layer adj depost$4 ald)	USPAT; US-PGPUB	2004/08/06 18:21
8	91010	((manufactur$4 fabricat$4 method)near15(contact$2))	EPO; JPO; DERWENT	2004/08/06 18:21
9	718	(atomic adj layer adj depost$4 ald)	EPO; JPO; DERWENT	2004/08/06 18:23
10	55	((contact$2 adj hole$2 via adj hole$2 through adj hole$2) same((barrier$2 liner$2)with (titanium aluminum "tio.sub.2" "al.sub.2o.sub.3")))and (atomic adj layer adj deposit$4 ald)	USPAT; US-PGPUB	2004/08/06 18:22
11	9	(((contact$2 adj hole$2 via adj hole$2 through adj hole$2) same((barrier$2 liner$2)with (titanium aluminum "tio.sub.2" "al.sub.2o.sub.3")))and (atomic adj layer adj deposit$4 ald)) not (((contact$2 adj hole$2 via adj hole$2 through adj hole$2) same((barrier$2 liner$2)with (titanium aluminum "tio.sub.2" "al.sub.2o.sub.3")))and (atomic adj layer adj depost$4 ald))	USPAT; US-PGPUB	2004/08/06 18:22
12	993	(atomic adj layer adj deposit$4 ald)	EPO; JPO; DERWENT	2004/08/06 18:24
13	29	(((manufactur$4 fabricat$4 method)near15(contact$2))) and ((atomic adj layer adj deposit$4 ald))	EPO; JPO; DERWENT	2004/08/06 18:25
14	0	(wet near3 etch$4)and ((((manufactur$4 fabricat$4 method)near15(contact$2))) and ((atomic adj layer adj deposit$4 ald)))	EPO; JPO; DERWENT	2004/08/06 18:25
15	10	(etch$4)and ((((manufactur$4 fabricat$4 method)near15(contact$2))) and ((atomic adj layer adj deposit$4 ald)))	EPO; JPO; DERWENT	2004/08/06 18:25
16	0	((barrier$2) near4 (bottom lower)) near7(etch$4) and ((contact$2 adj hole$2 via adj hole$2 through adj hole$2) same((barrier$2 liner$2)with (titanium aluminum "tio.sub.2" "al.sub.2o.sub.3")))and (((manufactur$4 fabricat$4 method)near15(contact$2)))	EPO; JPO; DERWENT	2004/08/06 18:28
17	3	((barrier$2) near4 (bottom lower)) and(etch$4) and ((contact$2 adj hole$2 via adj hole$2 through adj hole$2) and((barrier$2 liner$2)with (titanium aluminum "tio.sub.2" "al.sub.2o.sub.3")))and (((manufactur$4 fabricat$4 method)near15(contact$2)))	EPO; JPO; DERWENT	2004/08/06 18:29